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Photo IC Panasonic

PNA4701M

Photodiode with amplifier functions

For infrared remote control systems

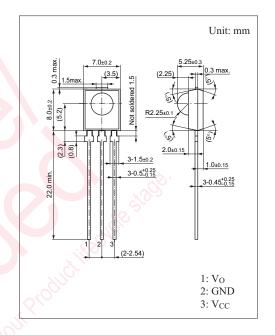
■ Features

- Center frequency f_O: 36.7 kHz
- ullet Operating supply voltage V_{CC} : 3.3 V(typ.)
- Adoption of visible light cutoff resin

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Operating supply voltage	V _{CC}	-0.5 to $+5$	V	
Power dissipation	P_{D}	200	mW	
Operating ambient temperature	T _{opr}	-15 to +70	°C	
Storage temperature	T _{stg}	-40 to +100	°C	
Soldering temperature *	T _{sol}	260	°C	





■ Electrical Characteristics $T_a = 25$ °C±3°C, $V_{CC} = 3.3$ V

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Operating supply voltage	V _{CC}	SING WILL SUG WAS THE	2.7	3.3	3.6	V
Output voltage low-level *2	V _{OL}	$L \le 7 \text{ m}, I_{OL} = 400 \mu\text{A}$		0.1	0.3	V
Output voltage high-level	V _{OH}	No signal condition, $I_{OH} = -2 \mu A$	2.86	3.3	_	V
Supply current	I_{CC}	6. 11.90.01.07.	0.6	0.8	1.0	mA
Maximum reception distance	L_{max}	78/12 4/20 VII V	7.0	_	_	m
Pulse width low-level *1	T_{WL}	L = 0.1 m to 7 m, 16 pulse	200	400	600	μs
Pulse width high-level *1	T_{WH}	· 10, eq.				
Center frequency	f_{O}	Mr. Tis.		36.7		kHz

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. *1: Burst wave form Figure 1
 - *2: Constant wave form Figure 2

400 μs

Carrier frequency: f_O

400 μs Figure 1

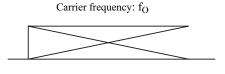
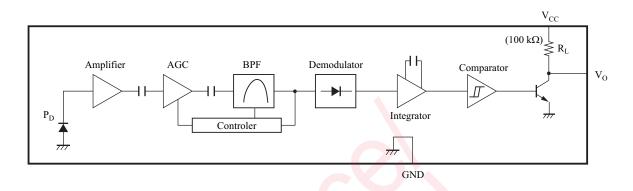


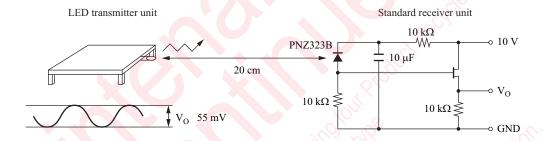
Figure 2

PNA4701M Panasonic

■ Block Diagram



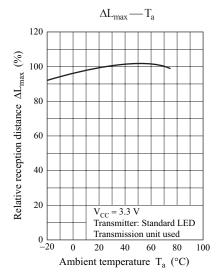
■ Panasonic Transmitter Specifications

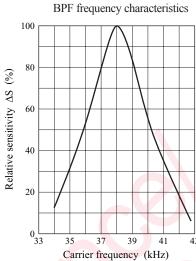


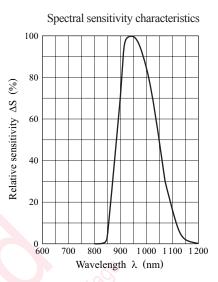
- 1. The output of the LED transmitter unit is adjusted so that the output standard receiver unit, V_O may be 55 mV when transmitting waves (duty = 50%) are output from the transmitter unit, where the sensitivity to infrared emitters (SIR) of PNZ323B is 0.53 mA when the irradiance H is 12.45 mW/cm².
- The maximum detection distance of this specification is guaranteed by T_{WH} and T_{WL} being within the limits when constant 16 pulses are transmitted with the output of the transmitter unit corresponded to the maximum detection distance in the system above.
 (The maximum detection distance is measured in the darkness without disturbing noises.)

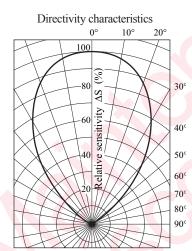
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